Call for Papers
a Session on

Smart and Sustainable Manufacturing

2016 ASME/ISCIE International Symposium on Flexible Automation (ISFA2016)
InterContinental Hotel & Conference Center
August 1-3, 2016, Cleveland, Ohio, USA

Session Technical Focus
The quest for sustainable manufacturing requires knowledge-based and data-driven approaches that exploit the wealth of information available to improve manufacturing processes/systems at minimum environmental, economic and societal costs. We cordially invite you to submit a paper to share your knowledge and expertise in all areas related to Smart and Sustainable Manufacturing. Papers from the industrial sector are particularly encouraged. The session welcomes both theoretical and applied papers in areas including, but not limited to:

- Smart and sustainable manufacturing systems, equipment and technologies
- Next-generation, intelligent robotics and automation
- Energy efficient manufacturing systems, equipment and technologies
- Mechatronic systems for smart and sustainable manufacturing
- Cloud-enabled manufacturing systems and applications
- Internet of Things, Industry 4.0 and/or Industrial Internet for manufacturing
- Assessment and monitoring of smart and sustainable manufacturing technologies

Paper Submission
The deadline for submission of your contribution to this session is February 29, 2016. Both short and long papers will be considered and reviewed. For short papers, please submit a summary of 1,000 words or less (short papers will be limited to 4 pages) and, for long papers, please submit a manuscript of no more than eight pages. All summaries and manuscripts should be submitted through the conference website at http://engineering.case.edu/conference/ISFA2016/.

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